

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

ltc2633hts8-hil2#trpbf

(Engineering Calculation)

TSOT-23

(printed on: 2020-07-11 17:14:32)

**TOTAL MASS (g) : 0.012478**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000710	1000000	56901.5546875		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.004582	975000	367215.40625		
		Iron (Fe)	7439-89-6	0.000113	24000	9056.16308594		
		Phosphorus (P)	7723-14-0	0.000001	300	80.1430358887		
		Zinc (Zn)	7440-66-6	0.000003	700	240.429122925		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.004699</b>	<b>1000000</b>	<b>376592.125</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000663	1000000	53109.9882812		
		<b>External Plating Total:</b>				<b>0.000663</b>	<b>1000000</b>	<b>53109.9882812</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000080	1000000	6411.44287109		
<b>Internal Plating Total:</b>				<b>0.000080</b>	<b>1000000</b>	<b>6411.44287109</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000206	800000	16509.4667969		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000051	200000	4087.29492188		
<b>Die Attach Total:</b>				<b>0.000257</b>	<b>1000000</b>	<b>20596.7617188</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.000347	58000	27809.6328125		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.005322	890000	426521.25		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000299	50000	23962.7675781		
		Carbon Black (C)	1333-86-4	0.000012	2000	961.716491699		
		<b>Encapsulation Total:</b>				<b>0.005980</b>	<b>1000000</b>	<b>479255.34375</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000089	1000000	7132.73046875		
					<b>TOTAL MASS (g) :</b>	<b>0.012478</b>		